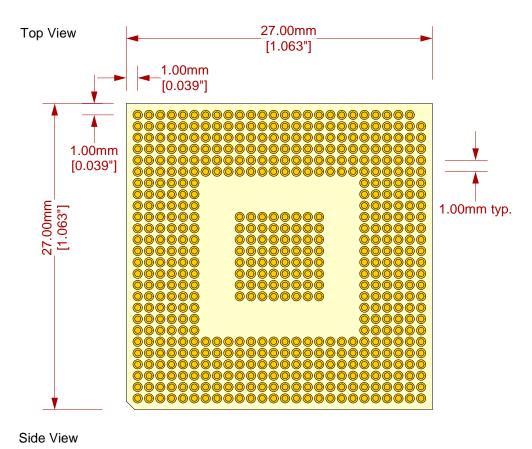
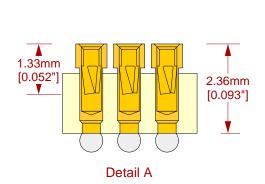
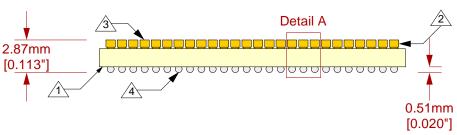
## **Patent Pending**







## RoHS COMPLIANT

## **CONTACT DATA**

Accepts 0.20mm - 0.33mm Diameter pins

3-finger

37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)

30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)

20/17 gram, extraction force (with 0.254mm0.203mm dia. pin)

1

Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. (RoHS)



Pins: material- Brass Alloy 360 1/2 hard; finish- $0.25\mu m [10\mu"]$  Au over  $1.27\mu m [50\mu"]$  Ni (min.).



Contacts: Beryllium Copper Alloy172, HT; Finish-0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).



Solder Balls Sn96.5Ag3.0Cu0.5

## Description: Giga-snaP BGA SMT Foot

543 position (1.0mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin asignment 1:1.

